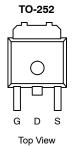


N-Channel 20-V (D-S)175 °C MOSFET

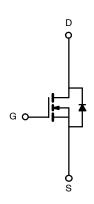
PRODUCT	RODUCT SUMMARY				
V _{DS} (V) r _{DS(on)} (Ω)		I _D (A) ^a			
00	0.006 @ V _{GS} = 4.5 V	65			
20	0.008 @ V _{GS} = 2.5 V	45			

FEATURES

- TrenchFET[®] Power MOSFET
- 175°C Maximum Junction Temperature
- 100% Rg Tested



Drain Connected to Tab



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	20			
Gate-Source Voltage		V _{GS}	±15	V		
	$T_{C} = 25^{\circ}C$		65			
Continuous Drain Current ^a	$T_{C} = 100^{\circ}C$		42			
Pulsed Drain Current		I _{DM}	200	A		
Continuous Source Current (Diode Conduction) ^a		IS	65			
	$T_{C} = 25^{\circ}C$		71			
Maximum Power Dissipation	T _A = 25°C	P _D	8.3 ^{b, c}	w		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 175	°C			

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	$t \le 10$ sec.		15	18	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	40	50	°C/W
Maximum Junction-to-Case		R _{thJC}	1.75	2.1	

Notes

- a. Package Limited
- b. Surface Mounted on 1" x 1" FR4 Board
- $\text{c.} \quad t \, \leq \, 10 \, \, \text{sec}$

Parameter	Symbol	Test Condition	Min	Тур ^а	Max	Unit	
Static							
Drain-Source Breakdown Voltage V(BR)DSS		$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \ \mu\text{A}$ 20					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.5		1.5	V	
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ±12 V			±100	nA	
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	DSS	V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 125 °C			50	μA	
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$	65			Α	
		V_{GS} = 4.5 V, I _D = 20 A		0.0045	0.006	<u> </u>	
Drain-Source On-State Resistanceb	r _{DS(on)}	V_{GS} = 4.5 V, I_D = 20 A, T_J = 125 $^\circ C$			0.007		
		V_{GS} = 2.5 V, I _D = 20 A			0.008		
Forward Transconductanceb	9fs	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 40 \text{ A}$	20			S	
Dynamic ^a							
Input Capacitance	C _{iss}			3660		pF	
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 20 V, f = 1 MHz		730			
Reverse Transfer Capacitance	C _{rss}			375			
Total Gate Charge ^c	Qg			26	35	nC	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 10 V, $~V_{GS}$ = 4.5 V, I_{D} = 40 A		5			
Gate-Drain Charge ^c	Q _{gd}			7			
Gate Resistance	Rg		1		3.7	Ω	
Turn-On Delay Time ^c	t _{d(on)}			20	35		
Rise Time ^c	t _r	$V_{DD} = 10 \text{ V}, \text{ R}_{1} = 0.25 \Omega$		120	190		
Turn-Off Delay Time ^c	t _{d(off)}	$\begin{array}{l} V_{DD} = 10 \text{ V}, \text{ R}_L = 0.25 \ \Omega \\ \text{I}_D \ \cong \ 40 \text{ A}, \text{ V}_{GEN} = 4.5 \text{ V}, \text{ R}_G = 2.5 \ \Omega \end{array}$		45	70	ns	
Fall Time ^c	t _f			20	35	1	
Source-Drain Diode Ratings ar	d Characteristi	c (T _C = 25°C)			•		
Pulsed Current	I _{SM}				100	А	
Diode Forward Voltage ^b	V _{SD}	I _F = 100 A, V _{GS} = 0 V		1.2	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 40 A, di/dt = 100 A/μs		35	70	ns	

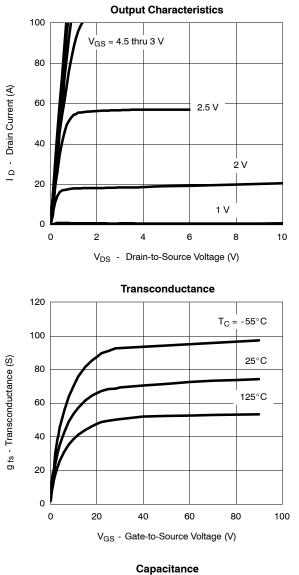
Bsemi

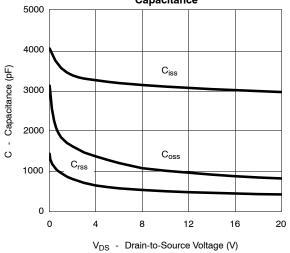
VBsemi

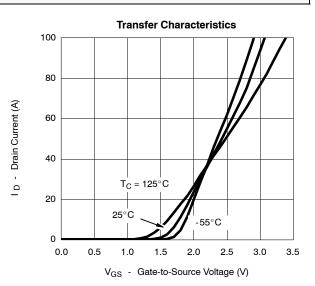
www



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)







On-Resistance vs. Drain Current 0.012 0.009 V_{GS} = 2.5 V 0.006 V_{GS} = 4.5 V 0.003

0.000

0

20

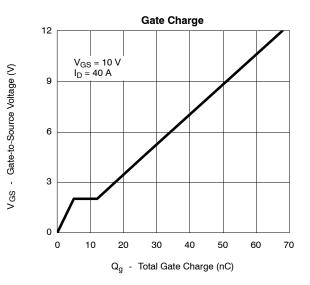
I_D - Drain Current (A)

60

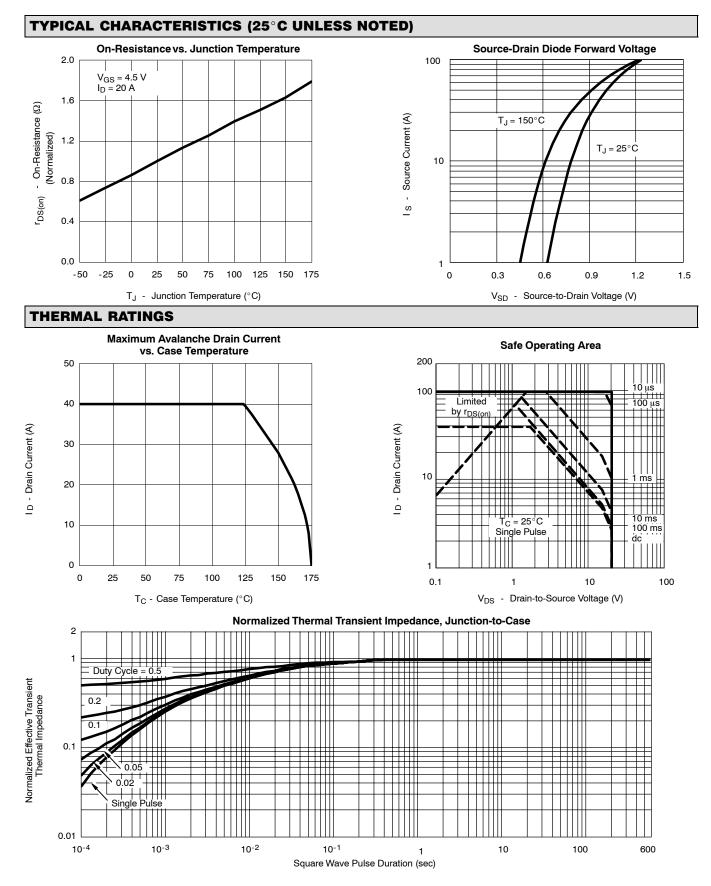
80

100

40

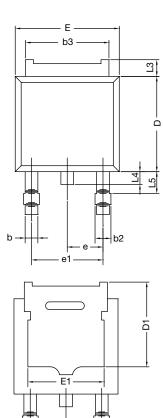


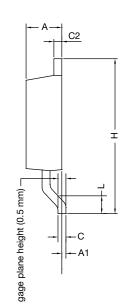






TO-252AA CASE OUTLINE





	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	2.28 BSC 0.090 BSC			
e1	4.56	4.56 BSC			
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12 DWG: 534	-0247-Rev. M, 7	24-Dec-12			

Note

• Dimension L3 is for reference only.



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